

L Number	Hits	Search Text	DB	Time stamp
1	57549	Kondo.inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 13:14
2	4	Kondo .inv. and thermal near expansion and mounting near apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 13:15
3	36	IIZAKA near ATSUSHI .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 13:17
4	0	IIZAKA near ATSUSHI .inv. and mouting near apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 13:17
-	2	5199855.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 10:59
-	16	mounting adj system and frame and driver and positioning near device and image adj taking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:32
-	5	mounting adj system and frame and driver and image adj taking and thermal adj expansion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 13:14
-	0	component adj mounting near apparatus and frame and driver and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:11
-	2	component adj mounting and frame and driver and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:11
-	0	component near apparatus and frame and driver and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:12

	2	c mponent near mounting and frame and driver and thermal adj expansion near system	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/09/26 07:12
	2	component near mounting and frame and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:12
	3	component near mounting and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:12
	947	component near mounting and thermal adj expansion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:13
	0	component near mounting and thermal adj expansion and image adj taken near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:13
	10	component near mounting and thermal adj expansion and image adj taking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:15
	36	29/740.ccls. and thermal near expansion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:16
	554	318/600.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:32
	2	6519835.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 11:12
	14241172	JP 05241660.pn.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/09/29 15:07

	3	thermal adj expansion near ballscrew and mounting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:15
	49	thermal adj expansion near mounting and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:19
	2	thermal adj expansion near mounting and apparatus and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:19
	47	thermal adj expansion and mounting near apparatus and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:20
	7	("4222036" "5383270" "5768759" "5992013" "6101709" "6195454" "6216341").PN.	USPAT	2003/09/29 15:25
	1	"4747198".PN.	USPAT	2003/09/29 15:27